



# METHOD STATEMENT

## WOOD FLOOR BONDING WITH SIKABOND® T 55(J)

SIKA LIMITED (VIETNAM)

BUILDING TRUST



# 1 SCOPE

Elastic bonding of wooden floor with SikaBond T55(J).



# 2 PRODUCTS

- **SikaBond® T55(J):**

One-component polyurethane adhesive for elastic bonding of timber floor

- **Sika® Primer 3:**

Adhesion promoter for wood containing high content of oils and resins

- **SikaFloor®-94:**

Two-component low viscosity epoxy resin binder for priming and repairing cement screed surface

- **Floor Topping Compound:**

Two-component SBR latex modified cement based self-leveling mortar

- **SikaFloor®-81 Epocem®**

Three-component, self-leveling epoxy-cement mortar for temporary moisture barrier and leveling.

- **Epocem®-Primer**

Two-component water based epoxy primer for SikaFloor®-81 Epocem®

- **Sikaflex®-11 FC**

One-component polyurethane adhesive for bonding of skirting

# 3 SYSTEMS DESCRIPTION

## Cordon application system:

- Is an economical and easy-to-apply system for wood floor bonding in residential and office building, where acoustics requirement is not very high.
- This application method can be used for solid wood board as well as 3-ply engineered wood and is suitable for all types of wood, including problematic woods like beech or bamboo.

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### Full surface bonding system

- Is a high safety adhesive system for use in residential, commercial or industrial buildings where very high adhesion and high acoustics performance is required.
- This application method can be used for solid and engineered wood floor, mosaic parquet, wood paving and industrial parquet. All types of wood, including problematic woods like beech or bamboo can be safely bonded.

## 4 TOOLS REQUIRED

- Surface preparation: grinding machine, industrial vacuum cleaner
- SikaBond® T55(J): caulking gun, notched trowel.

## 5 SURFACE PREPARATION

### Surface requirements and testing methods

- Moisture of the substrate: cement screed must have a moisture content below 2.5% which means a TRAMEX measurement below 4.
- Substrate strength of the surface: should be over 1.5 N/mm<sup>2</sup> The simplest way to test Substrate strength is to bond with SikaBond® T55(J) a piece of wood on the floor. Test after 3 days (pinch bar). If we have cohesion failure in the adhesive, the substrate is strong enough.
- Ensure that the substrate is dry, clean and free from all traces of loose materials and contaminants like oils, grease, laitance, etc.
- After checking the above requirements are met, the substrate must be grinded and thoroughly dry-cleaned with an industrial vacuum cleaner.
- Wood moisture content should not exceed 12%.
- Wooden planks should not be thinner than 6mm.
- Because each wood species is different, a bond test must be performed by Sika to assess the need of priming the back of the wood planks with Sika® Primer 3.

### Application of remedy products

- For cement substrate with moisture content above 2.5% and below 4% (TRAMEX measurement below >4 and <6), apply one coat of Sikafloor®-94 (see separate method statement)
- For cement substrate with moisture content above 4%, apply Sikafloor®- 81 Epocem® (see separate method statement) and then Sikafloor®-94.
- For substrate requiring leveling of 2-3mm, apply Sikafloor®-81 Epocem® (see separate method statement) and then Sikafloor®-94.
- For substrate requiring leveling of 4 to 10mm, apply Floor Topping Compound. (see Product Data Sheet), then Sikafloor®-94.
- Substrate with low strength (<1.5 N/mm<sup>2</sup>) must be consolidated with Sikafloor®-94.

### Alternative method with Plywood board

- For very uneven and low strength screed, plywood boards can be bonded or screwed. Then the timber floor must be bonded with the full surface system. (See case Study from Sika Argentina)

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## 6 BONDING APPLICATION

### Cordon Application

Following the adequate surface preparation (leveling, priming and cleaning):

- Place the opened unipack of SikaBond® T55(J) in the sealant gun.
- Holding nozzle at right angle to the substrate, extrude a triangular shaped bead of adhesive of approx. 10mm high x 8 mm wide at 150 mm distance.
- Press the wood pieces firmly into the adhesive before skinning time. 4. The wood should be firmly tapped together with a hammer using an impact block.
- A gap of 10-15mm between wood and wall should be observed.
- Weights to hold the wood in place until the adhesive is fully cured might be required (especially for solid wood).
- Fresh, uncured adhesive remaining on the wood floor must be removed immediately with a cloth impregnated of Sika® Remover 208.
- After a minimum of 18-24 hours waiting time the wood can be grinded and finished as required
- Consumption: one 600 ml unipack yield approx. 2m<sup>2</sup>.

### Full surface Application

Following the adequate surface preparation (levelling, priming and cleaning):

- Open the 2 kg unipack of SikaBond® T55(J) and pour the adhesive on the surface.
- Spread the adhesive evenly using a notched trowel.
- Press the wood pieces firmly into the adhesive before skinning time.
- The wood should be firmly tapped together with a hammer using an impact block.
- A gap of 10-15mm between wood and wall should be observed.
- Weights to hold the wood in place until the adhesive is fully cured might be required (especially for solid wood).
- Fresh, uncured adhesive remaining on the wood floor must be removed immediately with a cloth impregnated of Sika® Remover-208.
- After a minimum of 18-24 hours waiting time the wood can be grinded and finished as required
- Consumption: one 2kg unipack yield approx. 2m<sup>2</sup>

## 7 CLEANING

Caulking gun and notched trowel can be cleaned with Sika® Remover-208 after use .

## 8 SAFETY PRECAUTIONS

Wear protective clothing during application.

Sufficient ventilation must be provided in closed rooms

For more information, please refer to our Material Safety Data Sheet (available on request).

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## LEGAL NOTE

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the products suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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